

## Thermal RC network (Foster)

## SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base		-	-	2.44	K/W
	Cth <sub>1</sub>	2.010E-05 F		Д	4	
	Cth <sub>2</sub>	1.708E-04 F		<b>_</b>	<b>t</b> j	
	Cth <sub>3</sub>	1.888E-04 F			<b>_</b>	
	Cth <sub>4</sub>	7.066E-03 F				
	$Cth_5$	1.019E-03 F			$\int Rth_1 + Cth_1$	
	Cth <sub>6</sub>	9.129E-03 F				
	Cth <sub>7</sub>	9.134E-02 F		Г	ᠳ᠊᠊	
	Cth <sub>8</sub>	2.243E+02 F			$\int Rth_2 \rightleftharpoons Cth_2$	2
	Rth₁	4.007E-03 Ω				
	Rth <sub>2</sub>	6.986E-03 Ω		r		
	Rth <sub>3</sub>	4.049E-02 Ω			Rth3 🕇 Cth3	}
	Rth <sub>4</sub>	1.746E-02 Ω			┎	
	Rth₅	1.084E+00 Ω			<b>_</b>	
	Rth <sub>6</sub>	1.072E+00 Ω				1
	Rth <sub>7</sub>	2.058E-01 Ω				ŀ
	Rth <sub>8</sub>	4.457Ε-03 Ω	(	Р		
						5
					Rth6 $=$ Cthe	5
					Rth7 $=$ Cth7	,
Part:	BUK7M10-40E					
Date:	3/3/2016					5
Nodel Rth	2.44 K/W					
					t <sub>amb</sub>	
				v	001aal768	3

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